

**DESIGN/PROCESS CHANGE NOTIFICATION**

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

**Implementation of change:**

Expected First Shipment Date for Changed Product : Sep. 16, 2012

Expected First Date Code of Changed Product :1228

Description of Change (From) :

KA33V Product assembled in TO92 package using the current qualified copper(Cu) leadframe.

Description of Change (To) :

KA33V Product assembled in TO92 package using the alternate Iron(Fe) leadframe.

**> Bill of material**

Material	Current	Future
Lead frame Material	Copper	Fe + Cu plating
Die attach adhesive	Eutectic	Eutectic
Bond wire	Au	Au
Epoxy Molding Compound	LMC300TKL EME2500D3	LMC300TKL EME2500D3
Plating	Pure Tin	Pure Tin

**> LF pad size Comparison (Changed internal & external dimension)**

Package	Part	PAD Size	
		Current(Cu LF)	Future (Fe LF)
TO92	Center	3.00 X 1.19	3.56 x 2.11
		3.96 x 1.40	3.96 x 1.40
	Side	3.20 x 1.33	2.97 x 1.33
		3.80 x 1.50	3.80 x 1.50

Note > This dimension change is not affected Package outline drawing (SB-T-2487-B)

**> LF Composition Comparison**

Part	C	Fe	Si	Mn	Ni	Cu	P	S	Ag
SPCC (Fe base)	0.05	Re	0.044	0.213	0.65	0.78	0.16	0.16	
PMC90-1/2H (Cu base)	Re	0.05~0.15					0.025~ 0.040		

**> LF properties comparison**

Unit	Properties							
	Melting point	Density	Thermal conductivity	Thermal expansion	Coefficient of elastic	Tensile strength	Elongation	Hardness
	℃	g/cm <sup>3</sup>	Cal/cm/℃/sec	X10 <sup>-6</sup> / ℃(25~300)	Kg/mm <sup>2</sup>	Kgf/mm <sup>2</sup>	%	Hv
PMC90-1/2H	1082	8.94	0.870	16.9	12800	36~44	Min. 6	100~125
SPCC	1539	7.87	0.143	12	21000	60	15	190

Reason for Change:

To improve product availability and manufacturing flexibility.

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**Affected Product(s):**

KA33VBU	KA33VTA	
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Qualification Plan	Device	Package	Process	No. of Lots
Q20070371	KSB564CYTU	TO-92	PNP	2

Test Description:	Condition:	Standard :	Duration:	Results:
Autoclave	121C, 100%RH	JESD22-A102	96hrs	0/154
Temperature Humidity Bias Test	85C, 85%RH, -24V	JESD22-A101	168, 500,1000 hrs	0/154
Temperature Cycle	-65C, 150C	JESD22-A104	200, 500 cycles	0/154
Power Cycle	Delta Tj of 100 C, On/off = 2 min	JESD22-A105	1000, 5000	0/154

Qualification Plan	Device	Package	Process	No. of Lots
Q20070371	KSP44BU	TO-92	NPN	1

Test Description:	Condition:	Standard :	Duration:	Results:
Autoclave	121C, 100%RH	JESD22-A102	96hrs	0/77
Temperature Humidity Bias Test	85C, 85%RH, 100V	JESD22-A101	168, 500,1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	200, 500 cycles	0/77
Power Cycle	Delta Tj of 100 C, On/off = 2 min	JESD22-A105	1000, 5000	0/77